

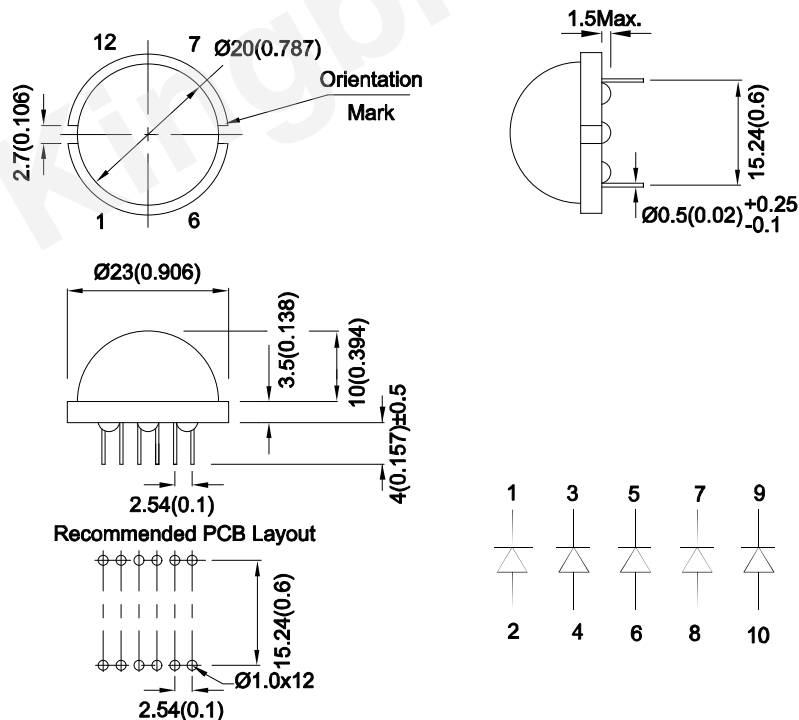
### Features

- 12 pins.
- High luminous intensity.
- Low power consumption.
- Wide viewing angle.
- Categorized for luminous intensity.
- Excellent on / off contrast.
- Easy mounting on P.C. board or sockets.
- Solid state reliability.
- RoHS compliant.

### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



## Selection Guide

| Part No. | Emitting Color (Material)       | Lens Type    | Iv (mcd) [2]<br>@ 10mA |      | Viewing<br>Angle [1] |
|----------|---------------------------------|--------------|------------------------|------|----------------------|
|          |                                 |              | Min.                   | Typ. | 2θ1/2                |
| DLC/6ID  | High Efficiency Red (GaAsP/GaP) | Red Diffused | 20                     | 49   | 120°                 |
|          |                                 |              | *6                     | *17  |                      |

### Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous Flux: +/-15%.

\* Luminous intensity value is traceable to CIE127-2007 standards.

## Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter                | Emitting Color      | Typ. | Max. | Units | Test Conditions |
|--------|--------------------------|---------------------|------|------|-------|-----------------|
| λpeak  | Peak Wavelength          | High Efficiency Red | 627  |      | nm    | IF=10mA         |
| λD [1] | Dominant Wavelength      | High Efficiency Red | 617  |      | nm    | IF=10mA         |
| Δλ1/2  | Spectral Line Half-width | High Efficiency Red | 45   |      | nm    | IF=10mA         |
| C      | Capacitance              | High Efficiency Red | 15   |      | pF    | VF=0V;f=1MHz    |
| VF [2] | Forward Voltage          | High Efficiency Red | 1.9  | 2.5  | V     | IF=10mA         |
| IR     | Reverse Current          | High Efficiency Red |      | 10   | uA    | VR = 5V         |

### Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

## Absolute Maximum Ratings at TA=25°C

| Parameter                     | Values                | Units |
|-------------------------------|-----------------------|-------|
| Power dissipation             | 75                    | mW    |
| DC Forward Current            | 30                    | mA    |
| Peak Forward Current [1]      | 160                   | mA    |
| Reverse Voltage               | 5                     | V     |
| Operating/Storage Temperature | -40°C To +85°C        |       |
| Lead Solder Temperature [2]   | 260°C For 3-5 Seconds |       |

### Notes:

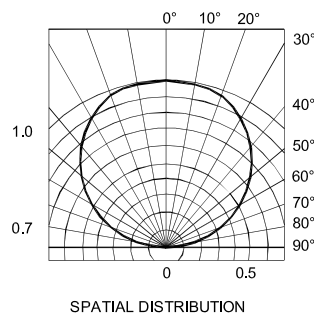
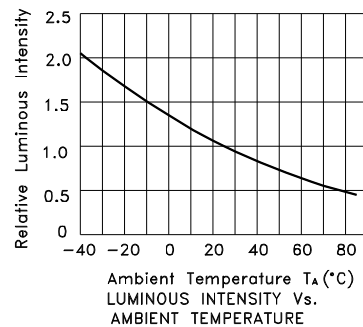
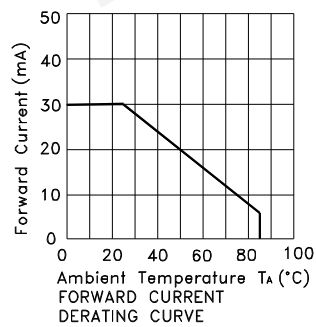
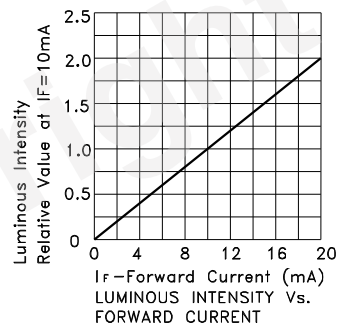
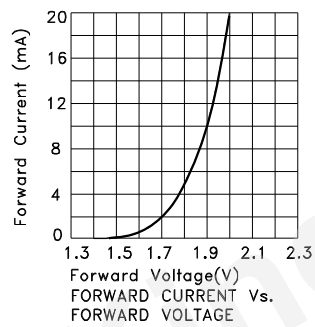
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

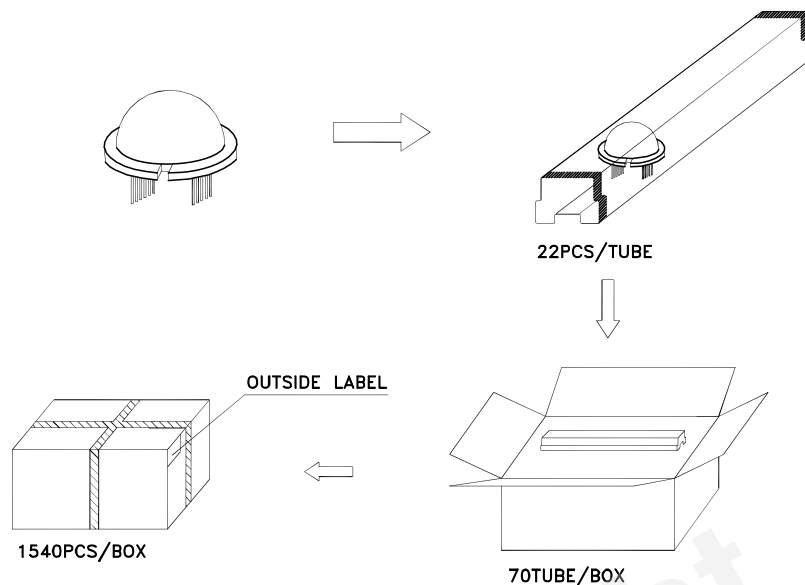


## High Efficiency Red DLC/6ID

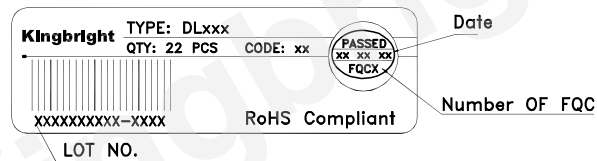


## PACKING & LABEL SPECIFICATIONS

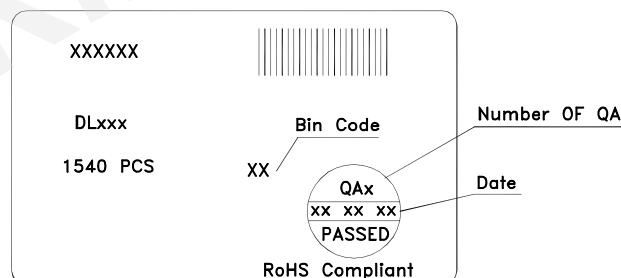
## DLC/6ID



### Inside Label On IC-tube



### Outside Label On BOX



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2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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## THROUGH HOLE DISPLAY MOUNTING METHOD

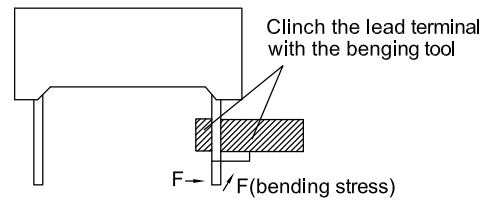
### Lead Forming

Do not bend the component leads by hand without proper tools.

The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



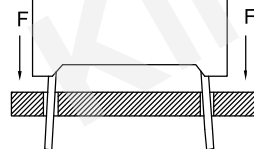
Not Recommended



Recommended

### Installation

1. The installation process should not apply stress to the lead terminals.
2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

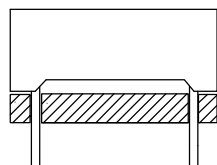


Not Recommended

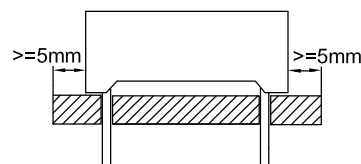


Recommended

3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



Not Recommended



Recommended

## Recommended Wave Soldering Profiles:



### Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

## Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

## CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning because they may damage the plastic parts.
3. The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
4. When water is used in the cleaning process, immediately remove excess moisture from the component with forced-air drying afterwards.

## CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the LEDs within the specified range.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.



3. The driving circuit should be designed to protect the LED against reverse voltages and transient voltage spikes when the circuit is powered up or shut down.
4. The safe operating current should be chosen after considering the maximum ambient temperature of the operating environment.
5. Prolonged reverse bias should be avoided, as it could cause metal migration, leading to an increase in leakage current or causing a short circuit.